

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10656613			
<b>Filing Date:</b>	04-Sep-2003			
<b>Title of Invention:</b>	HIGH PERFORMANCE ACTIVE AND PASSIVE STRUCTURES BASED ON SILICON MATERIAL BONDED TO SILICON CARBIDE			
<b>First Named Inventor/Applicant Name:</b>	Joseph H. Johnson			
<b>Filer:</b>	Benjamin Withrow/Jennifer Alkove			
<b>Attorney Docket Number:</b>	2867-661			
Filed as Large Entity				
<b>Utility under 35 USC 111(a) Filing Fees</b>				
<b>Description</b>	<b>Fee Code</b>	<b>Quantity</b>	<b>Amount</b>	<b>Sub-Total in USD(\$)</b>
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
Utility Appl issue fee	1501	1	1740	1740
<b>Extension-of-Time:</b>				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				1740